

GigaCAM Figure 3

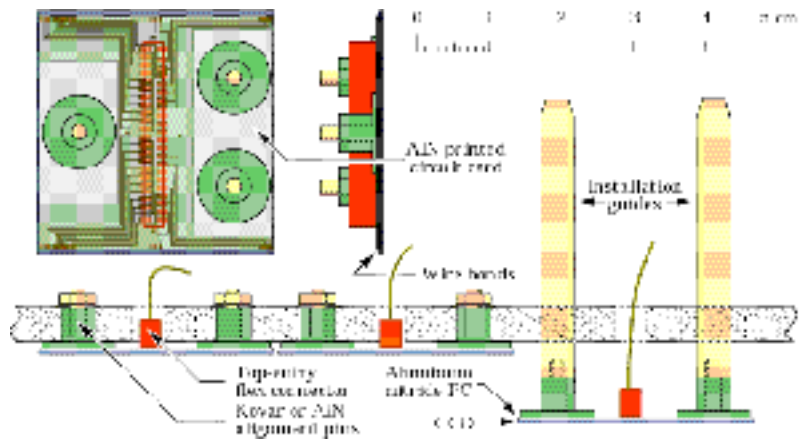


Figure 3. Conceptual design for fully-depleted CCD packaging. The CCD is cemented to a three-layer aluminum oxide substrate. The middle layer is a circuit board to which the cantilevered CCD pads are wire-bonded. Connections exit through the cold plate via a miniature connector in the center of the board. The third layer provides insulation and captures three indexing and mounting pins}.